

'*' indicates required field

? indicates online help

28th Technology Leadership Awards

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Disclaimer

28th PCB Technology Leadership Awards

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Disclaimer response *

Accept

Contact

If you have questions about the Technology Leadership Awards or design entry process, please contact the TLA administrators at pcb_tla@mentor.com.

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First name *

Last name *

Email address *

Company name *

Mentor/Siemens contact

Design category (Primary) *

Design category (Secondary)

Design name *

End-product description *

Unique features * ?

Critical constraints * ?

Intended use of the submitted design version *

- Proof of concept Debug / prototype Low-volume production High-volume production

Tool flow *

- Xpedition Enterprise PADS Professional PADS Standard/Plus Board Station Other

Tools used * ?

Advanced technologies ?

- RF/microwave Chip on board HDI/microvia Buried capacitance
 Flex/rigid-flex Flip chip Embedded passives Embedded actives
 Additive manufacturing Flexible hybrid electronics

Advanced product applications ?

- 5G IoT Virtual / augmented reality Nanotechnology
 Artificial intelligence / machine learning Autonomous vehicles / equipment

Design for... ?

- Signal integrity Power integrity Fabrication Assembly Test
 Reliability Cost

Units *

- Imperial (th) Imperial (in) Metric (um) Metric (mm)

Placement * ?

Select

Total usable board area * ?

th²

Board thickness *

th

Total metal layers *

Layer stack-up * ?

No file selected.

Stack-up definition * ?

Active components * ?

Passive components * ?

Total component area * ?

th²

Number of component pins *

Number of FPGAs *

Smallest pin pitch * ?

th

Fastest data rate (gbps) * ?

Nets testable after assembly (%) *

Test setup

- Point-to-point Functional (ICT)

Trace Width/Spacing

Minimum width * ?

th

Minimum spacing *

th

Typical width * ?

th

Typical spacing *

th

Via Pad/Size

Minimum hole size * ?

th

Minimum pad size *

th

Typical hole size * ?

th

Typical pad size *

th

Number of vias *

Number of nets *

Number of high-speed nets * ?

Number of voltage rails * ?

Number of ground nets *

Number of pin-to-pin connections *

Total trace distance *

th

Size of design team * ?

Design team names

Design team structure * ?

Total design time * ?

Architecture definition time (weeks) *

Schematic design time (weeks) *

Layout design time (weeks) *

Verification time (weeks) *

Manufacturing prep time (weeks) *

Did you meet the target design time? (How?) *

Verification types * ?

| Verifications | Action |
|--|--------|
| No Verifications have been added. Click on Add Verification below. | |

Add Verification

Design verification results ?

How did you collaborate with Mechanical? * ?

How did you collaborate with Manufacturing? * ?

Schematic / layout iterations *?

Layout / mechanical iterations *?

Layout / manufacturing iterations *?

Standards *?

Challenges *?

Tools *?

Additional comments ?

Attachments

Please attach any files related to your design. You may combine multiple files into one or attach up to three files separately. Alternatively, you can add a comment with an FTP address or request contact to upload.

File 1 * ?

No file selected.

File 2

No file selected.

File 3

No file selected.

Fabrication drawing * ?

No file selected.

Representative image * ?

No file selected.

Comments about attachments